

TLAR Series

Molding Power Inductors

Size 100760



FEATURES

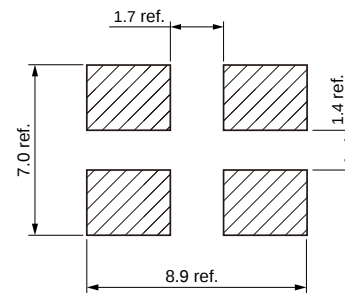
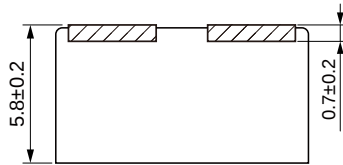
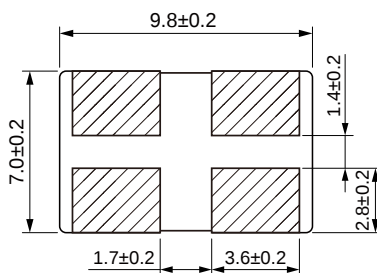
- Compliant for 100% Lead(Pb)-Free and RoHS.
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APPLICATION

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Dimensions: [mm]

Land Pattern: [mm]



Electrical Properties:

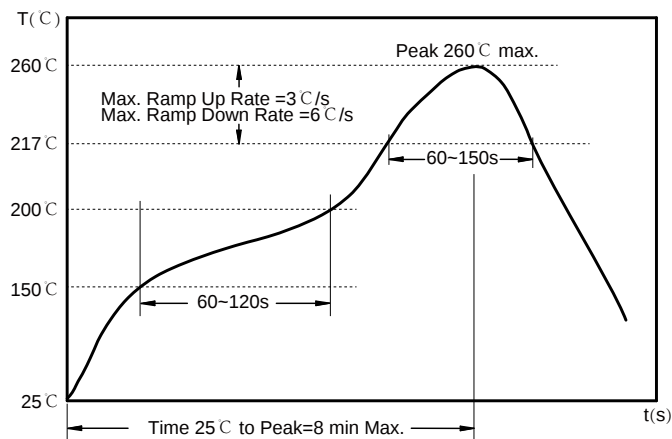
Part No	OCL	Inductance @ 100KHz/1V (μH)	DC Resistance (mΩ)		Temperature Rise Current (A)		Satura on Current (A)		Kps Typ.
			Typ	Max	Typ	Max	Typ	Max	
	1		0.14	0.16	68		88		
			0.14	0.16	68		88		

All test data is referenced to 25 °C ambient.

Saturation Current will cause L0 to drop approximately 30%.

Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$.

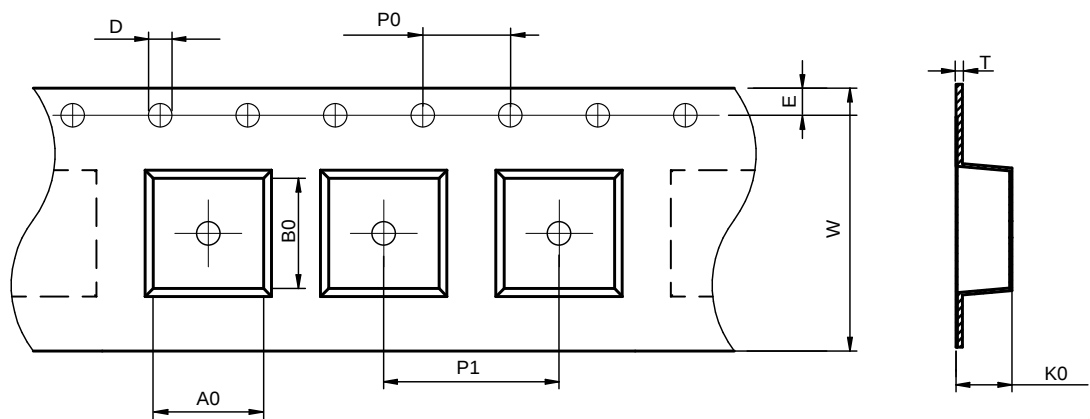
Soldering Reflow:



Preheat condition: 150 ~200 / 60~120 sec.
 Allowed time above 217 : 60~150 sec.
 Max temperature: 260 .
 Time within 5 of actual Peak Temperature: 30 max. sec.

Packaging Information:

Tape Dimension:

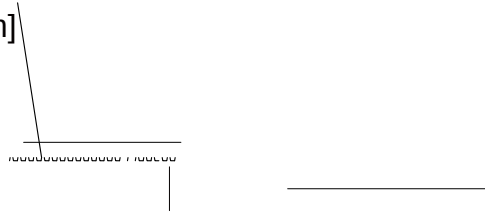


A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)

Product Marking:

Marking	Printing (Inductance)
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Reel Dimension: [mm]



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.